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TO:	FROM:
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☒ URGENT ☐ FOR REVIEW ☐ PLEASE COMMENT ☐ PLEASE REPLY ☐ PLEASE RECYCLE

NOTES/COMMENTS:

Per our conversation of even date, enclosed is copy of the patent application 98 7501 US 01
filed September 16, 2002

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTY.'S DOCKET: 98 P 7501 US 01

Do Not
Enter
And 3/24/03

In re the application of:)	
Ramachandran et al.)	Group Art: 1746
Serial No.: 09/204,706)	Examiner: A. Olsen
Filing Date: December 3, 1998)	
Title: REMOVAL OF POST-RIE POLYMER)	
ON Al/Cu METAL LINE)	

#230-NE
3/25/03
mwAMENDMENT UNDER 37 C.F.R. §1.116

Honorable Commissioner of Patents and Trademarks
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed September 10, 2002,
which rejected the claims in the above-identified patent
application, applicants respectfully request reconsideration,
based upon the amendments hereinafter set forth.

IN THE CLAIMS:

~~18~~ (5th Amendment) In a metal etch tool for removing
post-RIE polymer rails formed on a Al/Cu metal line of a
semiconductor structure, the improvement comprising:

[I] an integrated metal etch tool interfaceable with:

a) strip chamber means [for water only plasma] to strip
photo-resist of a semiconductor composite structure subsequent
to a RIE to limit thickness of sidewall polymer rails;

b) vacuum chamber means to chemically modify sidewall
polymer rails [by supplying a mixture of an etching gas/acid
neutralizing gas of] with HF/NH₃ to form a water soluble